



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)

Shunpei YAMAZAKI)

Serial No. 09/619,477)

Filed: July 19, 2000)

For: CONTACT STRUCTURE AND
SEMICONDUCTOR DEVICE)

) Group Art Unit: 2813

) Examiner: E. Kielin

CERTIFICATE OF MAILING

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Payton

AMENDMENT AND RESPONSE TO ELECTION REQUIREMENT

Honorable Commissioner for Patents

Washington, D.C. 20231

Sir:

In response to the Office Action of October 9, 2002, please amend the subject
application as follows:

IN THE CLAIMS:

Please amend claims 1-2, 4-6, 8-11, 13-14, 17-20, 22, 24-26, 28-29, 31-32, 34,
36-38, 40-41, 43, 45, 47-49 and 51-52 as follows:

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1. (Amended) A contact structure comprising:
a first substrate;
a second substrate;
a connecting wiring over said first substrate;
a wiring under said second substrate; and
an anisotropic conductive film between the first substrate and the second
substrate,
wherein said connecting wiring over said substrate and said wiring under
said second substrate are electrically connected by said anisotropic conductive film,
wherein said connecting wiring is a lamination film comprising a metallic film
and a transparent conductive film in contact with said metallic film, and